



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2014-02-17
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Giovanni Giacopello	<b>Representative Title</b>	AMS & IPD Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	KD6P*0158B16	A	BO2A	2014-02-17
Amount	UoM	Unit type	ST ECOPACK Grade	
34.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	3,4,4,1.0	8	gull wing	
Comment	Package: TSSOP 8 BODY 4.4 PITCH 0.65; MDF valid also for LM2904YPT; LM2904AYPT; LM258YPT; LM258AYPT			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-16 Dec 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	KD6P*0158B16					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	0.711	mg	supplier	die	Silicon (Si)	7440-21-3		0.698	mg	981716	20529
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.006	mg	8439	176
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.003	mg	4219	88
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.004	mg	5626	118
Leadframe	Copper & its alloys	14.497	mg	supplier	alloy	Copper (Cu)	7440-50-8		13.86	mg	956060	407647
Leadframe				supplier	alloy	Nickel (Ni)	7440-02-0		0.432	mg	29799	12706
Leadframe				supplier	alloy	Magnesium (Mg)	7439-95-4		0.022	mg	1518	647
Leadframe				supplier	alloy	Silicon (Si)	7440-21-3		0.094	mg	6484	2765
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.083	mg	5725	2441
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.003	mg	207	88
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.003	mg	207	88
Die attach	Other Organic Materials	0.327	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.298	mg	911315	8765
Die attach				supplier	glue or tape	acrylate	Proprietary		0.016	mg	48930	471
Die attach				supplier	glue or tape	Methacrylate	Proprietary		0.013	mg	39755	382
Bonding wire	Other inorganic materials	0.08	mg	supplier	wire	Copper (Cu)	7440-50-8		0.08	mg	1000000	2353
encapsulation	Other Organic Materials	18.385	mg	supplier	mold compound	Silica, vitreous	60676-86-0		16.124	mg	877019	474235
encapsulation				supplier	mold compound	Epoxy resin A	EC 413-900-7		0.735	mg	39978	21618
encapsulation				supplier	mold compound	Epoxy resin B	29690-82-2		0.735	mg	39978	21618
encapsulation				supplier	mold compound	phenol resin	Proprietary		0.552	mg	30024	16235
encapsulation				supplier	mold compound	carbon black	1333-86-4		0.055	mg	2992	1618
encapsulation				supplier	mold compound	additive	Proprietary		0.184	mg	10008	5412